

ABSTRACT OF THE DISCLOSURE

A vacuum or hermetic packaged micromachined or MEMS device and methods for manufacturing the device so that the device has at least one substantially vertical feedthrough are provided. In a first embodiment, the method
5 includes: providing a MEMS device fabricated on a first side of a substrate and located within a vacuum or hermetic cavity; forming at least one hole completely through the substrate between first and second sides of the substrate after the step of providing; and forming a path of electrically conductive material connecting the
10 MEMS device and the second side of the substrate through the at least one hole to form the at least one substantially vertical feedthrough.